

ABSTRACT

A substrate bonding apparatus for use in fabricating LCD devices substantially prevents substrates held to upper stages from sagging. The substrate bonding apparatus may, 5 for example, include upper and lower stages having a plurality of passages for holding respective substrates; suction force applying means having one end mounted within each passage for transmitting a suction force to operably proximate portions of a substrate, wherein the one end of the suction force applying means is projectable from within each passage to a predetermined distance from the stage; and a vacuum pump for providing a 10 suction force to the suction force applying means.